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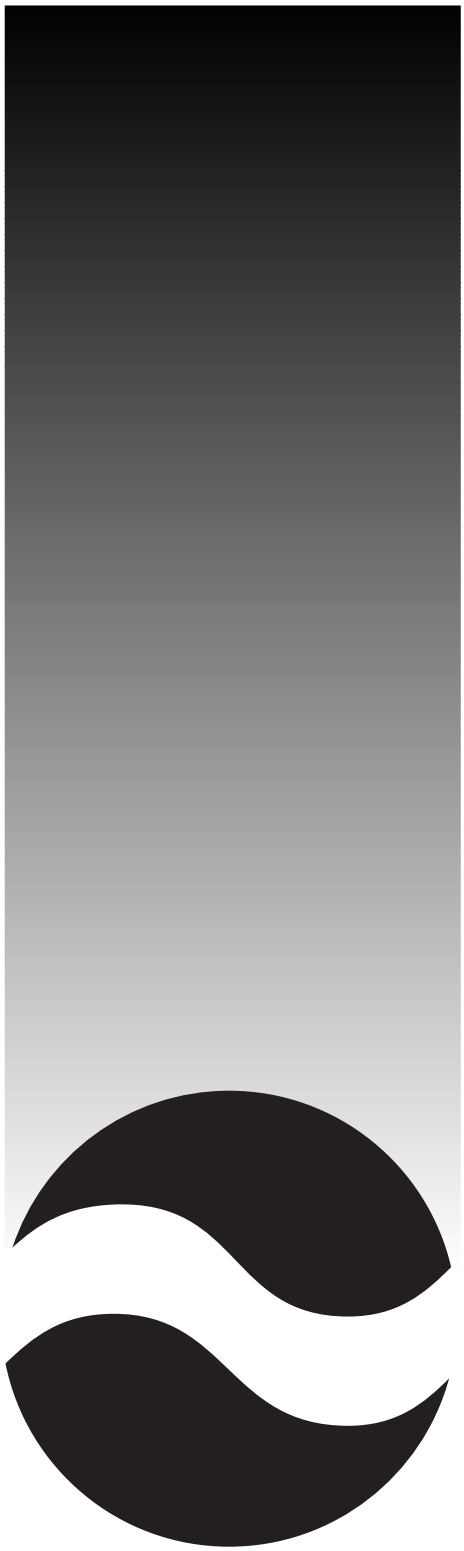
Requirements for Soldered Electrical and Electronic Assemblies



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Requirements for Soldered Electrical and Electronic Assemblies

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Requirements for Soldered Electrical and Electronic Assemblies

1 GENERAL

1.1 Scope This standard prescribes practices and requirements for the manufacture of soldered electrical and electronic assemblies. Historically, electronic assembly (soldering) standards contained a more comprehensive tutorial addressing principles and techniques. For a more complete understanding of this document's recommendations and requirements, one may use this document in conjunction with IPC-HDBK-001, IPC-A-610 and IPC-HDBK-610.

When J-STD-001 is cited or required by contract, the requirements of IPC-A-610 do not apply unless separately or specifically required. When IPC-A-610 is cited along with J-STD-001, the order of precedence is to be defined in the procurement documents.

1.2 Purpose This standard describes materials, methods and acceptance criteria for producing soldered electrical and electronic assemblies. The intent of this document is to rely on process control methodology to ensure consistent quality levels during the manufacture of products. It is not the intent of this standard to exclude any procedure for component placement or for applying flux and solder used to make the electrical connection.

1.3 Classification This standard recognizes that electrical and electronic assemblies are subject to classifications by intended end-item use. Three general end-product classes have been established to reflect differences in producibility, complexity, functional performance requirements, and verification (inspection/test) frequency. It should be recognized that there may be overlaps of equipment between classes.

The user (see 1.8.13) is responsible for defining the product class. The product class should be stated in the procurement documentation package.

CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically the end-use environment would not cause failures.

CLASS 3 High Performance Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

1.4 Measurement Units and Applications All dimensions and tolerances, as well as other forms of measurement (temperature, weight, etc.) in this standard are expressed in SI (System International) units (with Imperial English equivalent dimensions provided in brackets). Dimensions and tolerances use millimeters as the main form of dimensional expression; micrometers are used when the precision required makes millimeters too cumbersome. Celsius is used to express temperature. Weight is expressed in grams.

1.4.1 Verification of Dimensions Actual measurement of specific part mounting and solder fillet dimensions and determination of percentages are not required except for referee purposes. For the purposes of determining conformance to this specification, all specified limits in this standard are absolute limits as defined in ASTM E29.

1.5 Definition of Requirements The word **shall** is used in the text of this document wherever there is a requirement for materials, preparation, process control or acceptance of a soldered connection.

Where the word **shall** leads to a hardware defect for at least one class, the requirements for each class are annotated in text boxes located adjacent to that occurrence in the text. These boxes are summarized in Appendix A. Appendix A identifies each listed condition for each class as either ''Defect,'' ''Process Indicator,'' ''Acceptable,'' or ''No Requirement Established.'' In case of a discrepancy between requirements in the text boxes and Appendix A, requirements listed in the text boxes take precedence.

Line drawings and illustrations are depicted herein to assist in the interpretation of the written requirements of this standard. Text takes precedence over the figures.

IPC-HDBK-001, a companion document to this specification, contains valuable explanatory and tutorial information compiled by IPC Technical Committees that is relative to this specification. Although the Handbook is not a part of this specification, when there is confusion over the specification verbiage, the reader is referred to the Handbook for assistance.